

<b>PCN Number:</b>	20160822001	<b>PCN Date:</b>	08/23/2016
<b>Title:</b>	Die Revision Change on Select MSP430FE42x MCU Devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	08/23/2016	<b>Estimated Sample Availability:</b>	Date provided at sample request.
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
		<input type="checkbox"/>	Mechanical Specification
		<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Process

**PCN Details**

**Description of Change:**

Texas Instruments Incorporated is announcing an information only notification for select MSP430FE42x MCU devices. A minor die revision change was performed to improve LFO for higher ESR crystal support and to correct MPY2 Errata. The design change does not affect the specified form fit or function of the device. There will be no accompanying changes to the device specifications.

Affected devices are listed in the product affected section of this document.

**Reason for Change:**

LFO improvement and MPY2 Errata fix

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Changes to product identification resulting from this PCN:**

Die Rev designator for the affected devices will change as shown in the table and sample label below:

	<b>Current</b>	<b>New</b>
<b>Wafer fab</b>	<b>Die Rev [2P]</b>	<b>Die Rev [2P]</b>
TSMC-WF3	E	K
TSMC-F10	H	K

Sample product shipping label (not actual product label)



MADE IN: Malaysia  
2DC: 20:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:  
ITEM: 39  
**LBL: 5A (L)T0:1750**



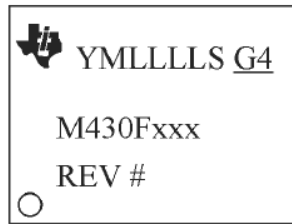


(1P) SN74LS07NSR  
 (Q) 2000 (D) 0336  
 (31T) LOT: 3959047MLA  
 (4W) TKY (1T) 7523483S12  
 (P) **(2P) REV:** (V) 0033317  
 (20L) CSO: SHE (21L) CCO:USA  
 (22L) ASO: MLA (23L) ACO: MYS

Topside Symbolization for the affected devices will be as shown below:

**PM64**

**LQFP (PM), 64 Pin**



- YM = Year and Month Date Code
- LLLL = Assembly Lot Code
- S = Assembly Site Code
- # = DIE Revision
- = Pin 1

**Product Affected**

MSP430A093IPMR	MSP430FE423IPMR	MSP430FE425IPMR	MSP430FE427IPM
MSP430FE423IPM	MSP430FE425IPM	MSP430FE427CY	MSP430FE427IPMR

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>